

Table 1: Signal Pin Reference

<i>Signal</i>	<i>Type</i>	<i>Level</i>	<i># Pins</i>	<i>Description</i>
DIN, NDIN	In	ECL	2	Data Input and Data Reference, On-chip 50% Termination
MK, NMK	Out	ECL	2	Data Density Differential Outputs
NIOUT	Out	—	1	Laser Modulation Current Output (Complementary)
IOUT	Out	—	1	Laser Modulation Current Output (To Laser Cathode)
VSS	Pwr	Pwr	2	Negative Voltage Rail
GND	Pwr	Pwr	5	Positive Voltage Rail
VIP	In	DC	1	Modulation Gate Node
MIP	In	DC	1	Modulation Source Node
VIB	In	DC	1	Bias Gate Node
MIB	In	DC	1	Bias Source Node
IBIAS	Out	DC	1	Laser Bias Output (To Laser Cathode)
CLK, NCLK	In	ECL	2	Clock Input and Clock Reference, On-chip 50% Termination
DINTERM	In	DC	1	Data Reference
CLKTERM	In	DC	1	Clock Reference
DCC	In	DC	1	Duty Cycle Control, Leave Floating
SEL	In	DC	1	Clk/Non-clk Data Select
Total Pins	—	—	24	

Table 2: Mux Select Logic Table

<i>SEL</i>	<i>Mode Select</i>
V _{SS}	Clocked Data In
GND	Non-clocked Data In
N/C	Non-clocked Data In

Table 3: Absolute Maximum Ratings

<i>Symbol</i>	<i>Rating</i>	<i>Limit</i>
V _{SS}	Negative Power Supply Voltage	V _{CC} to -6.0V
T _j	Maximum Junction Temperature	-55C to + 125C
T _{stg}	Storage Temperature	-65C to +150C

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Table 4: High Speed Inputs and ECL Outputs

Symbol	Parameter	Min	Max	Units	Conditions
V _{IN}	Single-ended Input Voltage Swing	300	1500	mVp-p	V _{CM} = -2.0V
V _{CM}	Differential Input Common Mode Range	-2.3	-1.3	V	V _{SS} = -5.2V
V _{OH}	ECL Output High Voltage	-1200	—	mV	50 Ohms to -2.0V
V _{OL}	ECL Output Low Voltage	—	-1600	mV	50 Ohms to -2.0V
V _{IN}	On-Chip Terminations	35	65	Ohms	—

Table 5: Recommended Operating Conditions

Symbol	Parameter	Min	Typ	Max	Units	Conditions
GND	Positive Voltage Rail	—	0	—	V	—
V _{SS}	Negative Voltage Rail	-5.5	-5.2	-4.9	V	—
T _C	*Operational Temperature	-40	—	85**	C	Power dissipation = 1.3W
T _J	Junction Temperature	—	—	125	C	—

*Lower limit of specification is ambient temperature and upper limit is case temperature.

**See section "Calculation of the Maximum Case Temperature" for detailed maximum temperature calculations.

Table 6: Power Dissipation

Symbol	Parameter	Min	Typ	Max	Units	Conditions
I _{VSS}	Power Supply Current (VSS)	—	—	120	mA	V _{SS} = -5.5, I _{MOD} = I _{BIAS} = 0 mA, MK/NMK open circuit
P _d	Total Power Dissipation	—	—	700	mW	V _{SS} = -5.5, I _{MOD} = I _{BIAS} = 0 mA, Rload = 25 Ohms to GND, MK/NMK terminated 50Ω to -2V

Table 7: Laser Driver DC Electrical Specifications

Symbol	Parameter	Min	Typ	Max	Units	Conditions
I _{BIAS}	Programmable Laser Bias Current	2	—	100	mA	—
I _{MOD}	Programmable Modulation Current	2	—	100	mA	—
V _{IB}	Laser Bias Control Voltage	—	—	V _{SS} + 2.1	V	I _{BIAS} = 50 mA
V _{IP}	Laser Modulation Control Voltage	—	—	V _{SS} + 2.1	V	I _{MOD} = 60 mA
V _{OCM}	Output Voltage Compliance	—	GND -3V	—	V	V _{SS} = -5.2V

Table 8: Laser Driver AC Electrical Specifications

Symbol	Parameter	Min	Typ	Max	Units	Conditions
t_r t_f	Output Rise and Fall Times	—	—	100	ps	25 Ohm load, 20%-80%, 20mA < I_{MOD} < 60mA, I_{BIAS} = 60mA
t_{su}	t Setup Data to Clock	—	50	90	ps	—
t_h	t Hold	20	50	—	ps	—

Table 9: Package Thermal Specifications

Symbol	Parameter	Min	Typ	Max	Units	Conditions
θ_{JCC}	Thermal Resistance from Junction to Case	—	25	—	°C/W	Ceramic Package

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Calculation of the Maximum Case Temperature

The VSC7927 is designed to operate with a maximum junction temperature of 125°C. The rise from the case to junction is determined by the power dissipation of the device. The power dissipation is determined by the V_{SS} current plus the operating I_{MOD} and I_{BIAS} currents.

The power of the chip is determined by the following formula:

$$P_D = (-V_{SS} * I_{SS}) + ((V_{IOUT} - V_{SS}) * I_{MOD}) + ((V_{IBIAS} - V_{SS}) * I_{BIAS})$$

For example with:

$$\begin{aligned} V_{SS} &= -5.2V \\ I_{MOD} &= 40mA \\ I_{BIAS} &= 20mA \\ V_{IBIAS} &= -2.0V \\ V_{IOUT} &= -2.0V \end{aligned}$$

$$P_D = (-5.2 * 150mA) + ((5.2 - 2.0) * 40mA) + ((5.2 - 2.0) * 20mA)$$

$$P_D = 780mW + 128mW + 64mW = 972mW$$

The thermal rise from junction to case is $\theta_{JC} * P_D$. For the metal glass package, $\theta_{JC} = 32^\circ C/W$. Thus the thermal rise is:

$$32^\circ C/W * 1.336W = 31.1^\circ C$$

The maximum case temperature is:

$$125^\circ C - 31.1^\circ C = 93.9^\circ C$$

The absolute maximum power dissipation of the device is at:

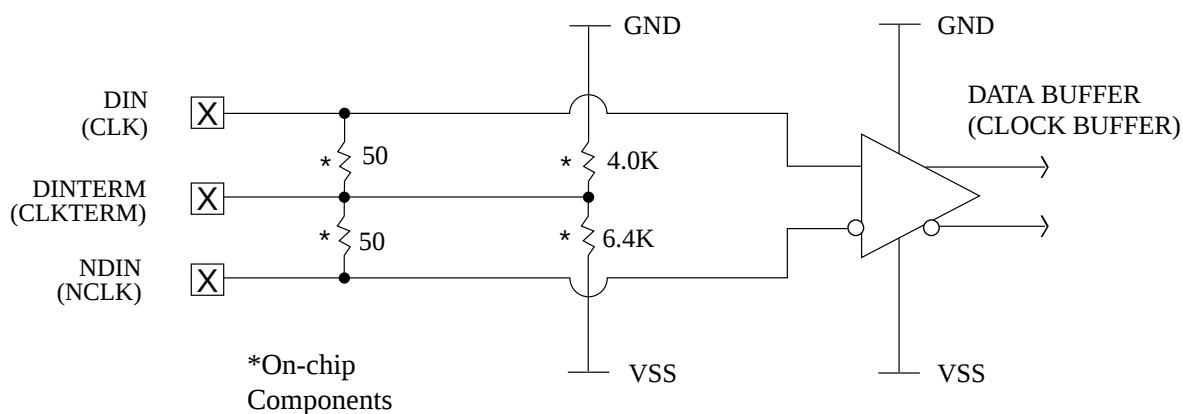
$$\begin{aligned} V_{SS} &= -5.5V \\ I_{MOD} &= 60mA \\ I_{BIAS} &= 50mA \\ V_{IBIAS} &= 0V \\ V_{IOUT} &= 0V \end{aligned}$$

$$P_D = (5.5 * 150mA) + (5.5 * 60mA) + (5.5mA * 50mA) \quad P_D = 1.43W$$

This will net a maximum junction to case thermal rise of: $1.43W * 32^\circ C/W = 45.8^\circ C$

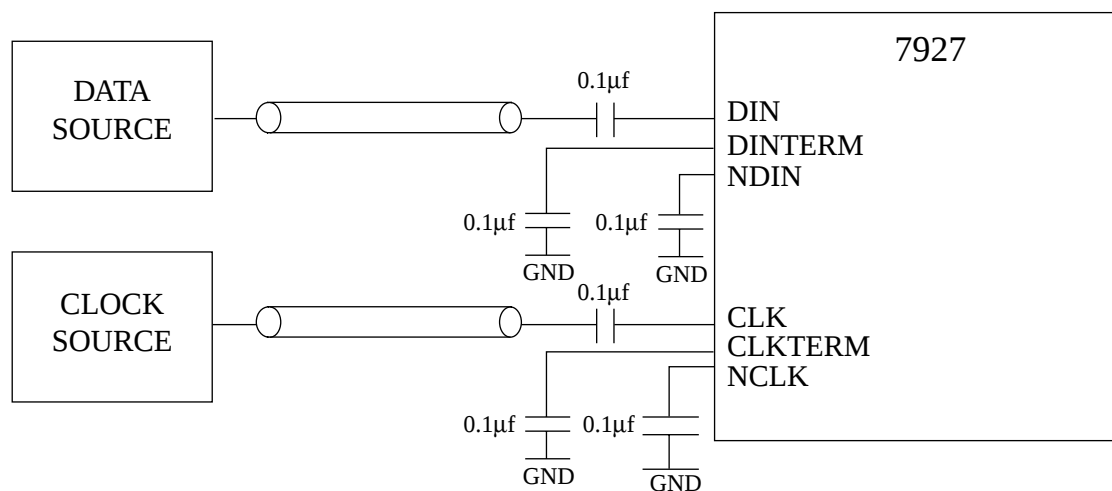
This situation will allow maximum case temperature of: $125^\circ C - 58^\circ C = 79.2^\circ C$

Figure 1: On-chip Data and Clock Input Configuration



DINTERM to -2.0V for Differential ECL Inputs

Figure 2: Single Ended Operation



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Figure 3: Single Ended AC Coupled

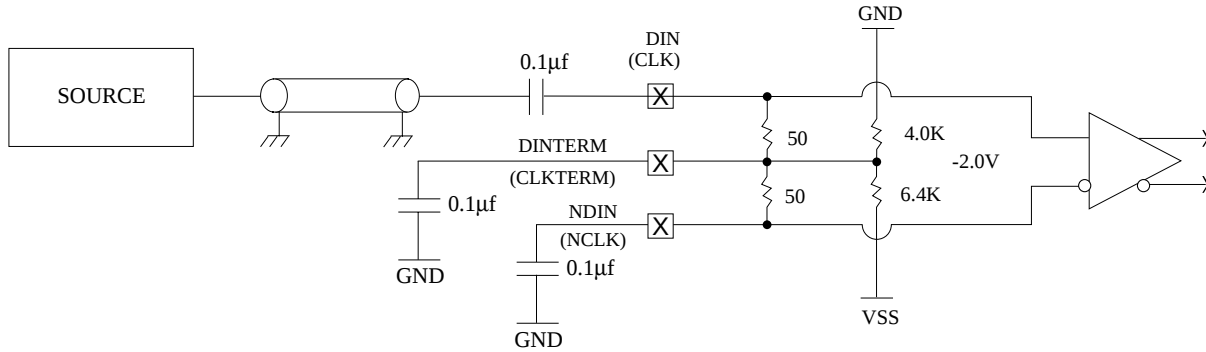


Figure 4: Differential AC Coupled

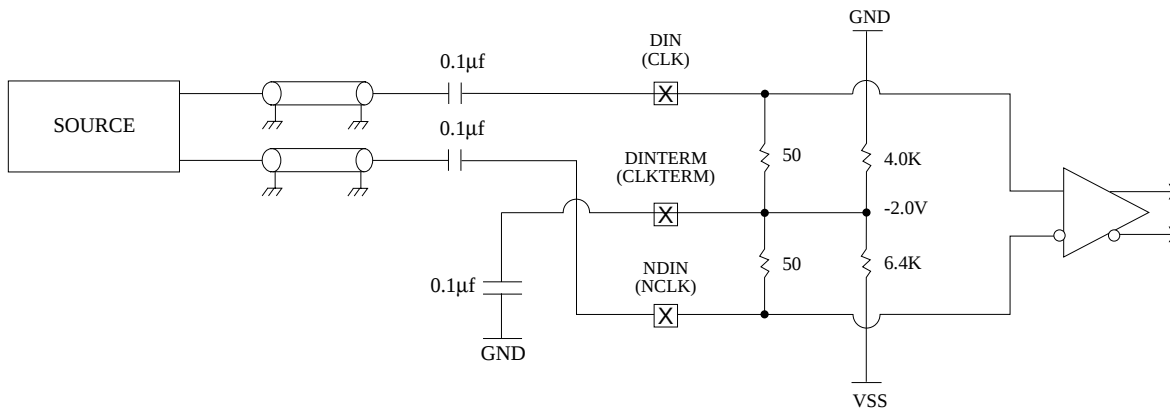


Figure 5: Differential DC Coupled

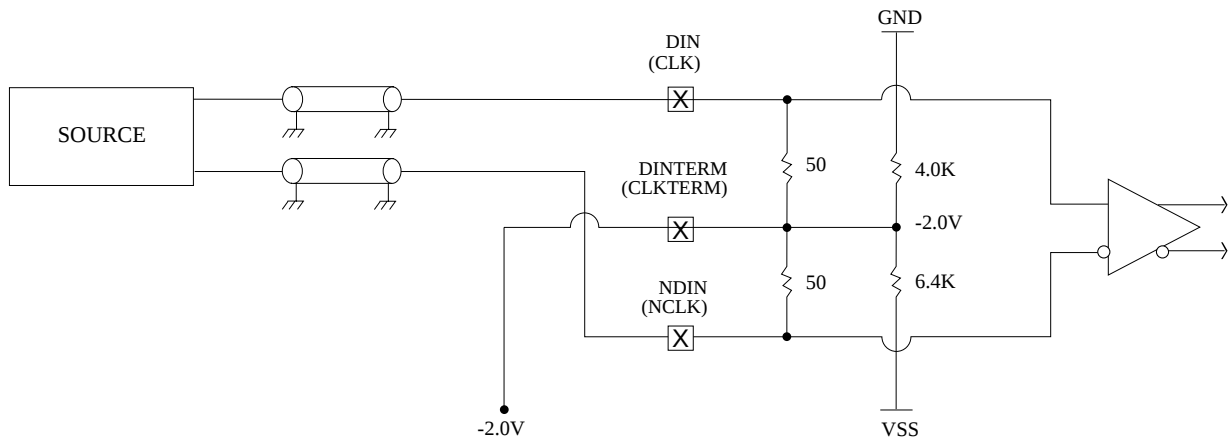
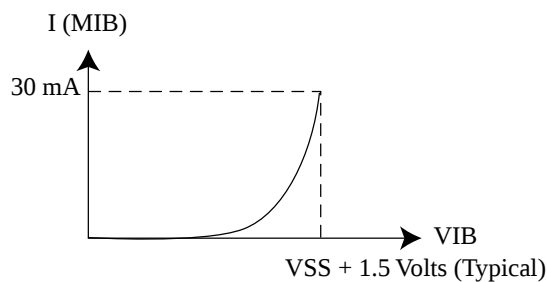
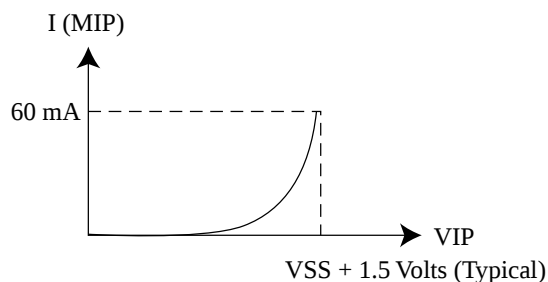


Figure 6: Control Signals VIP and VIB

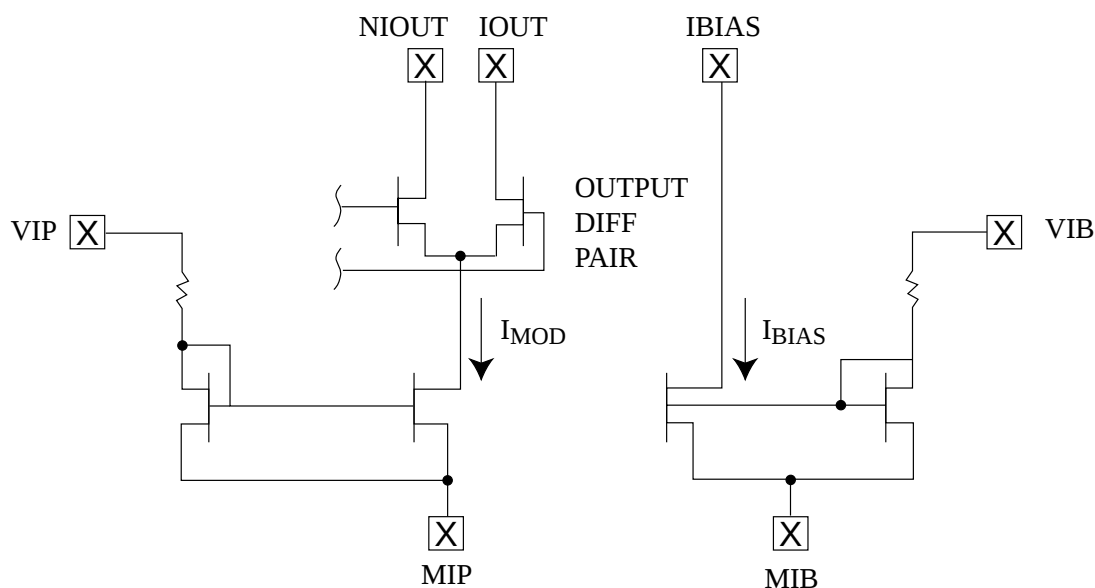


Typical Bias Current v.s. Bias Voltage



Typical Modulation Current v.s. Modulation Voltage

Figure 7: Simplified Output Structure

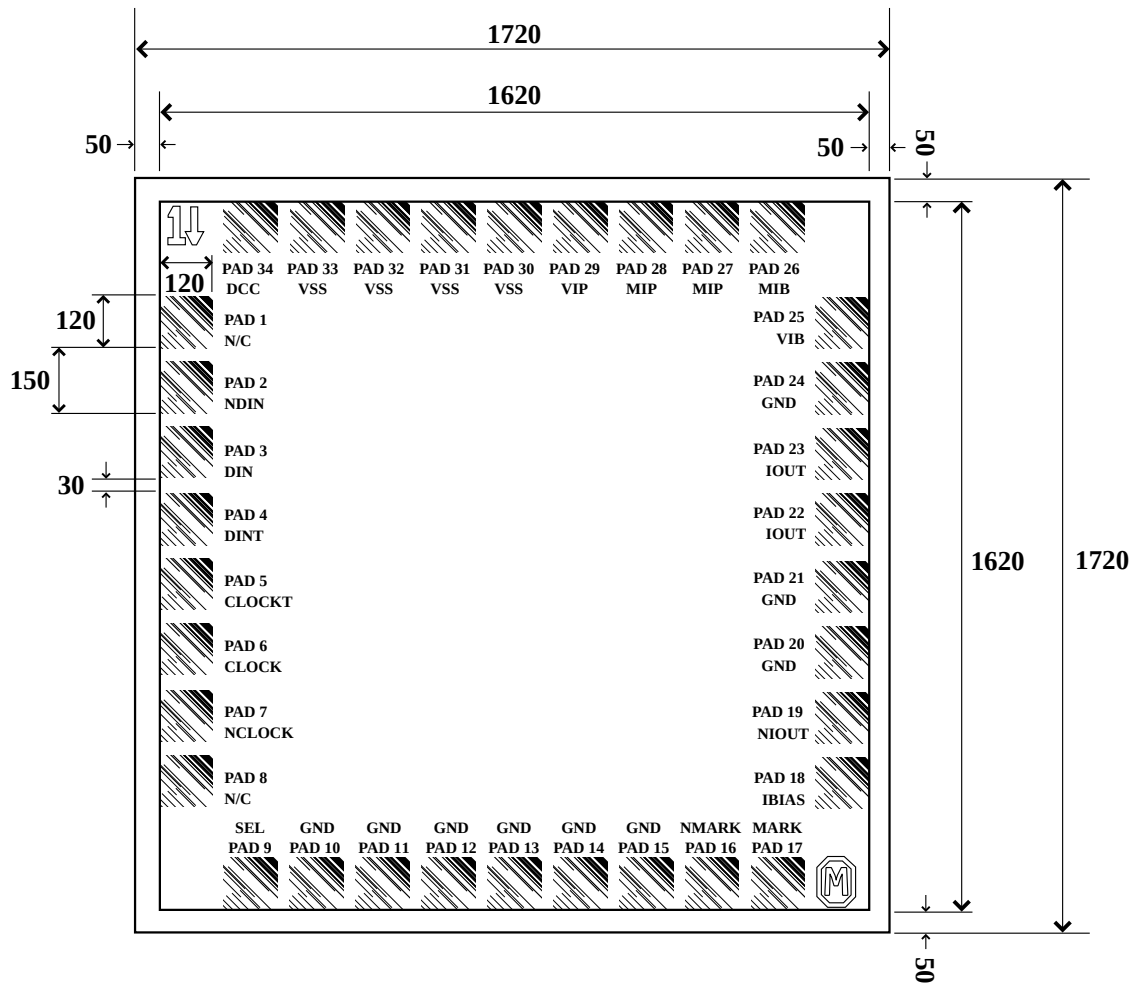


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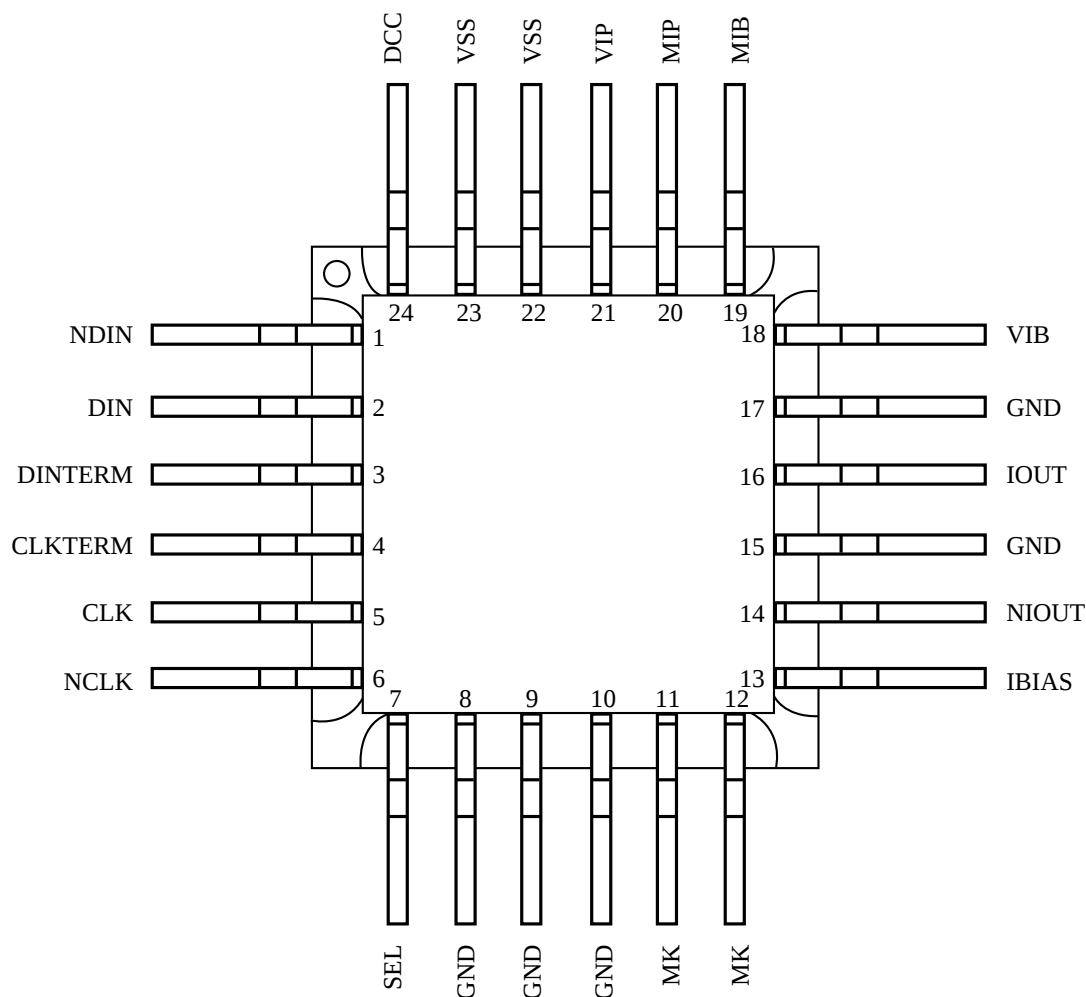
Figure 8: Pad Assignments for VSC7927 Die



Notes:

- 1) Die size = 1620 X 1620
- 2) Actual die size = 1720 X 1720 (After the die are sawn up)
- 3) Pad size = 120 X 120 Microns
- 4) Pad pitch = 150
- 5) Space between pads = 30

Pin Diagram for 24 Pin Ceramic Package



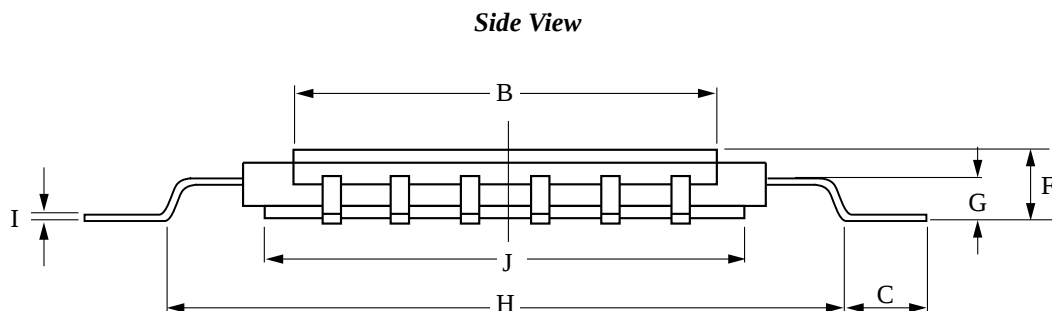
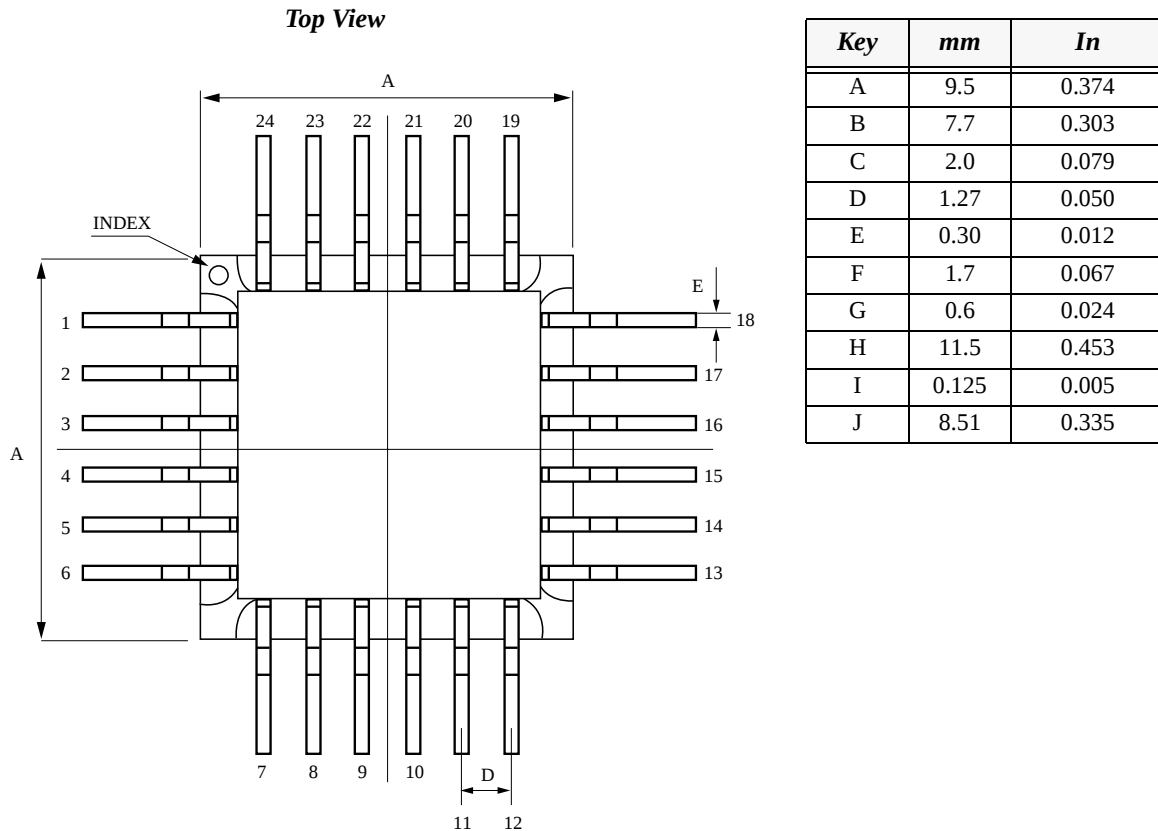
Note: Package lid and bottom heat spreader are electrically connected to GND within the package.

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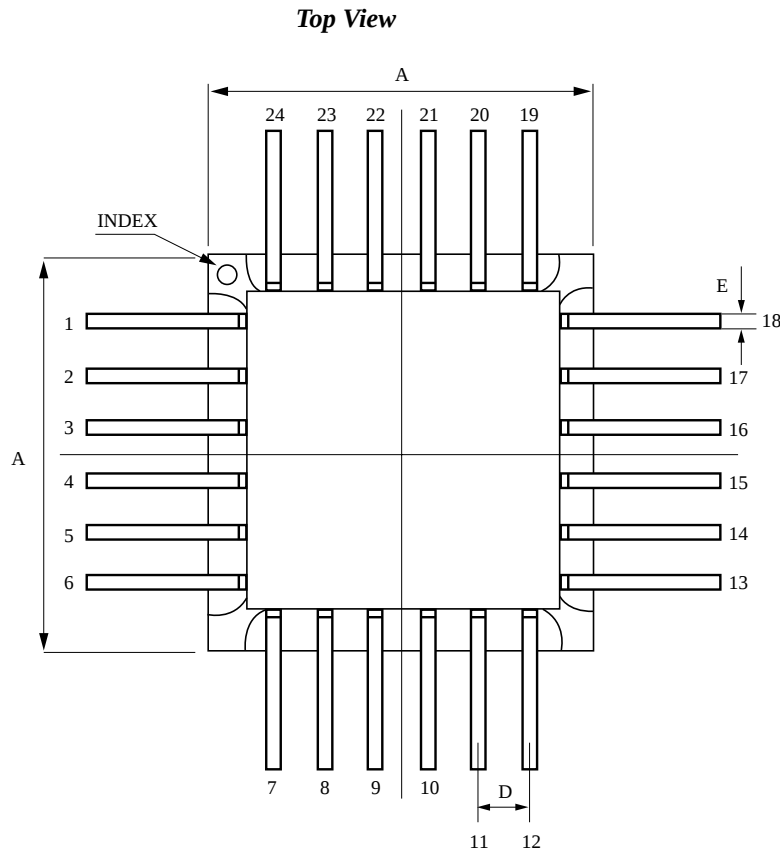
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Package Information - 24 Pin Ceramic Package (Formed Leads)

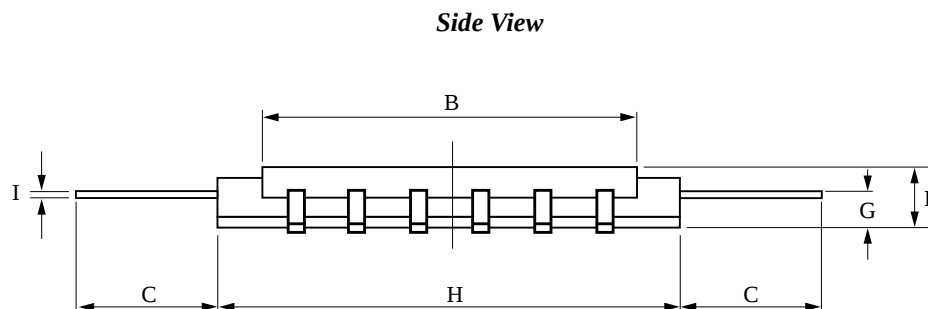


NOTES: Drawing not to scale.
Package #: 101-000-0 Issue #:1

Package Information - 24 Pin Ceramic Package (Straight Leads)



Key	mm	In
A	9.5	0.374
B	7.7	0.303
C	5.8	.230
D	1.27	0.050
E	0.30	0.012
F	1.7	0.067
G	0.6	0.024
H	9.53	0.375
I	0.125	0.005
J	8.51	0.335



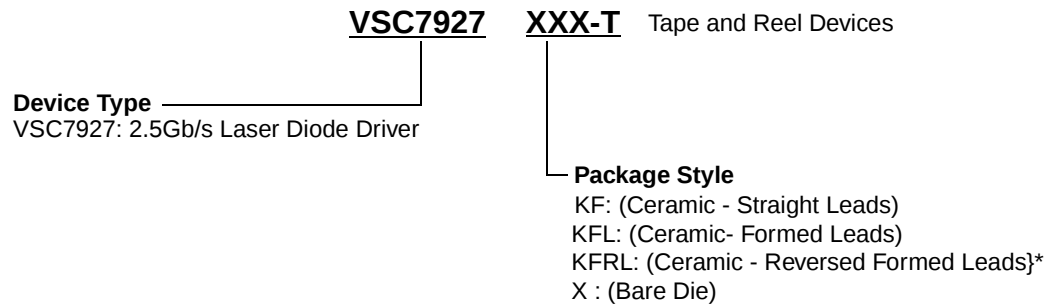
NOTES: Drawing not to scale.
Package #: 101-000-0 Issue #:1

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Ordering Information

The order number for this product is formed by a combination of the device number, and package style.



*Optional Reversed Formed Leads: Package leads have the same profile and dimensions, but heat spreader is away from board. Please contact the factory for additional information.

Notice

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